

TSMC-01-1004

October 6, 2003

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/615,745 07/09/03

Amos Chou et al.

A NOVEL BIOLOGICAL APPROACH FOR
FORMING LOW-K DIELECTRICS

Grp. Art Unit:

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

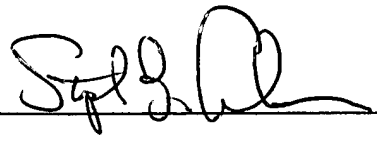
The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on October 10, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 10/10/03

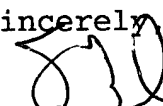
U.S. Patent 6,204,202 to Leung et al., "Low Dielectric Constant Porous Films," teaches a method for forming porous films of low dielectric constant, specifically nanoporous silica films.

U.S. Patent 6,159,842 to Chang et al., "Method for Fabricating a Hybrid Low-Dielectric-Constant Intermetal Dielectric (IMD) Layer with Improved Reliability for Multilevel Interconnections," teaches a method for fabricating a low-k intermetal dielectric layer by first covering the metal lines with a protective low-k fluorine doped oxide, filling the lined gaps so formed with a porous, spun-on dielectric layer, then covering the entire structure with a more dense dielectric layer to provide the needed structural integrity.

U.S. Patent 6,265,321 to Chooi et al., "Air Bridge Process for Forming Air Gaps," teaches a method for confining air-plugs between metal interconnects.

U.S. Patent 5,171,713 to Matthews, "Process for Forming Planarized, Air-Bridge Interconnects on a Semiconductor Substrate," teaches the fabrication of a multilevel integrated circuit in which successively formed levels are separated by polyimide layers through which interconnects pass.

Sincerely,


Stephen B. Ackerman, Reg. #37761

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant